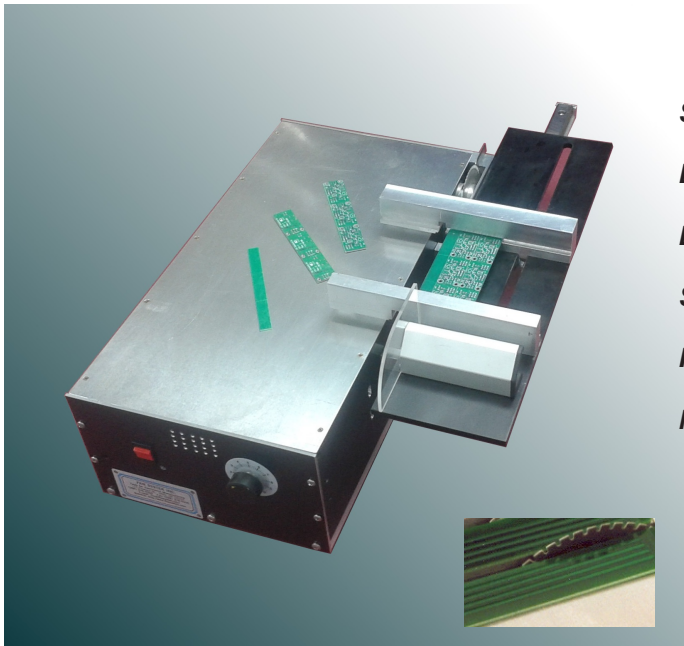


## Cut PCB Panels without scoreline and with overhanging components

Low stress singulation of PCBs with sensitive components



**Safely Singulate PCB panels without Scoreline.**

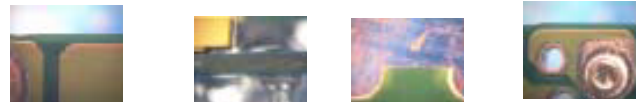
**Depanelize Boards with overhanging components.**

**Built in Dust Extraction Channel.**

**Singulate panels up to 12.2" long.**

**Positioning Tooling for a variety of panel types.**

**Mechanically indexed tooling plate for quick alignment**



Micro view of cut tabs. Accuracy +/- .001

The S100 is a diamond blade depaneling saw for singulating assembled PCBs. The saw blade is a 2.95" (75mm) diameter .021" thick cutting blade. Blade guards and support blades can be used to assure that the board is set at just the right height for cutting through the material without touching overhanging components.

Use the S100 in production, for PCB panels with sensitive components near the scoreline, or in the lab for a variety of pre-production and development purposes. Tooling includes guide rails for production boards with pre-scored lines as well as an optional micro adjustable table with position indicators for smaller panels.

This saw can be used to singulate PCBs without scorelines, or to singulate PCBs with overhanging components on the parting line. Since the cutting depth can be set to just cut through the PCB itself, any components which overhang the parting line will remain intact. The working area of the saw is covered by a dust extraction nozzle.

This prevents operator access to the cutting action while it is taking place. Additional dust extraction is underneath the path of the cutting blade.

Printed circuit boards can be placed onto a front and back rail and brought to an adjustable position stop for cutting, or tooling plates for quick and accurate change-over can be used. A light and magnifying alignment sight helps to position the cutting line precisely along the path of the blade.

